Leaded solder wire
IF **14-06**, IF **14-09**, IF **14-14**

SnPb(Ag), halide free, no-clean solder wire

Description:

Interflux® **IF 14-06, 14-09** and **14-14** are SnPb(Ag), no-clean solder wires that contain no rosin, no halides and are recommended when soldering in **class 3** (IPC-A-610).

Since the body of the **IF 14** flux carrier can evaporate by heat (rather than carbonising), residues can easily be cleaned.

Availability

Flux type: IF 14
Flux content: 0,6—0,9—1,4 % w/w

alloy	melting point	diameters 0,35	0,50	0,70	1,00	1,50	2,00
Sn60Pb40	183°C—191°C	●	●	●	●	●	●
Sn63Pb37	183°C	●	●	●	●	●	●
Sn62Pb36Ag2	179°C	●	●	●	●	●	●

● = available ● = upon request

More information:

Key advantages:

- Reduced contamination of tools, equipment, due to the low flux content
- Low non sticky residue, easily removable by hand
- No colophony fumes
- Classification to IPC and EN: **RE L0**
- Absolutely halogen free
- Long tip-life
- Long product history
- Very good wetting on Cu, Ag, Sn …

Work instructions

Manual soldering

The working temperature is between 320°C and 360°C. For more dense metals like Nickel, the temperature may be elevated to 400°C.

Choose the correct soldering tip: to reduce the thermal resistance, it is important to create a large contact surface with the component and solder pad.

The use of a good soldering station is important in order to always have the correct temperature on the soldering joint. Use a soldering station with a response time as short as possible.

Heat up the surfaces of both component and island simultaneously. Slightly touch with the solder wire, the point where component lead, soldering island and soldering tip meet (the small quantity of solder ensures a drastic lowering of the thermal resistance). Add subsequently without interruption, the correct amount of solder close to the soldering tip without touching the tip. It is important that no solder wire is making contact with the soldering tip during soldering to avoid flux spitting and premature flux consumption!

Handling

Storage

Store the solder wire in a clean environment at ambient temperature.

Handling

To avoid spool and wire damage, handle package with care.

Test results

conform EN 61190-1-3(2007) and IPC J-STD-004(A)

Property	Result	Method
Chemical		
flux designator	**RE / L0**	J-STD-004A
	F-SW 33	DIN 8511
	1.2.3	ISO 9454
qualitative copper mirror	**pass**	J-STD-004A IPC-TM-650 2.3.32
qualitative halide		
silver chromate (Cl, Br)	**pass**	J-STD-004A IPC-TM-650 2.3.33
	pass	TR-TSY-000078 13.1.4
spot test (F)	**pass**	J-STD-004A IPC-TM-650 2.3.35.1
	pass	TR-TSY-000078 13.1.5
quantitative halide	**0,00%**	J-STD-004A IPC-TM-650 2.3.35
Environmental		
SIR test	**pass**	J-STD-004 IPC-TM-650 2.6.3.3
	pass	TA-NWT-000078 13.1.4
qualitative corrosion, flux	**pass**	J-STD-004A IPC-TM-650 2.6.15
electro chemical migration	**pass**	TA-NWT-000078 13.1.5

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Packaging

Spools of 100g, 500g and 1000g

Trade name: IF 14-06 Leaded, Halide Free, No-Clean Solder Wire
IF 14-09 Leaded, Halide Free, No-Clean Solder Wire
IF 14-14 Leaded, Halide Free, No-Clean Solder Wire

D i s c l a i m e r

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